



Fast and easy solution to potting and encapsulating electronic components



The fast and easy solution for potting and encapsulating electronic components

Sealing components with potting and encapsulating compounds prevents corrosion and ensures long-term integrity of a device, but using traditional methods, such as epoxy resins or silicone can prove time consuming, costly and inefficient.

A new manufacturing process has been developed for a black polyamide potting compound that can be dispensed through conventional 12mm (½") hot melt glue guns. This process has been specifically designed for the electronic, automotive and aerospace industries.

Benefits

Tecbond adhesives have a number of advantages over traditional potting and encapsulating methods:

- **Fast:** the adhesive is quick to apply, and fast to set
- **Easy to use:** no mixing, no waste, and no consumable parts
- **Clean:** clean application, with no messy residue once the adhesive has cooled
- **Cost effective:** fast and accurate application with no cleaning or flushing required
- **Efficient:** no need for ovens to accelerate the curing process
- **No shelf life:** tecbond adhesives are clean to handle and can be stored for long periods without risk of expiry
- **No chemicals or solvents:** tecbond adhesive is completely environmentally friendly, non-toxic and contains no solvents



Disadvantages of other systems

Other system like epoxy resins or silicones can prove to be:

- Time consuming
- Costly
- Inefficient

Potting & encapsulating adhesives

Tecbond hot melt adhesive provides instant, permanent bonding on a vast range of materials without the use of harmful solvents.

The tecbond 7718FR adhesive has a very low viscosity, so flows easily into the smallest cavities. Black in colour, it will prevent the encapsulated components being visible and, in turn, further protect your technology. The adhesive is fire retardant, has a very fast setting time, and is suitable for:

- **Component stabilisation**
- **Attaching components to PC boards**
- **Fixing and securing**
- **Coil terminating battery packs**
- **Vibration protection**
- **Strain relief of cables**
- **Potting**
- **Wire staking**

The glue is supplied in air-tight, resealable foil bags to stop exposure to moisture and keep the glue in optimum condition for use.

Tecbond 7718FR is supplied in 12mm (½") x 250mm (10") glue sticks and packed in 10 stick resealable foil bags (10 x 10 stick bags per carton).



Formulation	Description	Colour	Open time	Viscosity
7718FR	Black, low viscosity potting and encapsulation polyamide adhesive	Black	Short	Low

Tec™ glue guns

Tec glue guns are low-cost capital items, highly portable, and designed to be totally reliable in tough industrial environments. Just load the tool with glue and it will melt it on demand as the trigger is pulled.

tec 305-12

Light industrial 12mm (½") glue gun, lightweight and easy to use, illuminated on/off switch, removable stand, adjustable full hand trigger and replaceable nozzle.

Melt rate	900g (2lbs)/hr
Glue size	12mm (½") glue stick
Voltage	110-240V
Wattage	20W (150W)
Heater	PTC
Temp Control	Self-regulating heater
Hotmelt gun °C (°F)	195°C (380°F)
Lowmelt gun °C (°F)	130°C (265°F)
Power cable	2m (6½ ft)
Weight	250g (9oz)
Packaging	PET blister (10 per ctn)



tec 305 potting and encapsulating kit available



gas-tec 600

The gas-tec 600 is a totally portable, robust compact hot melt glue gun that runs on butane gas. It does not require mains electricity or batteries but operates on gas, which can be easily refuelled from cigarette lighter refill cans.

Melt rate	1.7kg (3.7lbs)/hr
Glue size	12mm (½") glue stick
Voltage	Gas powered
Wattage	185W (equivalent)
Heater	Catalytic
Temp Control	Thermostatic gas valve
Hotmelt gun °C (°F)	195°C (380°F)
Lowmelt gun °C (°F)	n/a
Power cable	Cordless
Weight	390g (14oz)
Packaging	PET blister (10 per ctn)



gastec 600 potting and encapsulating kit available



tec 820-12

Adjustable temperature, heavy duty medium size 12mm (½") glue gun. Robust and easy to use, fast recovery, medium output, 2 minute warm up time & illuminated on/off switch.

Melt rate	2.5kg (5½lbs)/hr
Glue size	12mm (½") glue stick
Voltage	120V and 230V
Wattage	250W
Heater	Cartridge
Temp Control	User adjustable thermostat
Hotmelt gun °C (°F)	Adjustable 130-200°C (265-390°F)
Lowmelt gun °C (°F)	Covered above
Power cable	3m (10 ft)
Weight	500g (18oz)
Packaging	Plain box (10 per ctn)



tec 820 potting and encapsulating kit available



Accessories

Tec mat



TEC MAT

Reference	Description	tec 305	gastec 600	tec 820
TEC MAT	Silicone rubber drip mat protects work surface. Size 200mm x 200mm x 1.75mm	■	■	■

Carry case



DDP003-SPARES

Multi-purpose carry-case, can be used with gas-tec 600, tec 305 & most tec 800 series guns. Can also take the tec mat and other accessories.

Reference	Description	tec 305	gastec 600	tec 820
DDP003-SPARES	Carry case	■	■	■

Gun stands



FFS003-SPARES



MDC009



SK-800-MAGSTAND

Reference	Description	tec 305	gastec 600	tec 820
FFS003-SPARES	For craft/light industrial tools, 300 series	■	■	■
MDC009	For 600 & most 800 series tools (can be wall mounted)	■	■	■
SK-800-MAGSTAND	For most 800 series guns only, smaller stand attaches to metal plate or other metal surfaces	■	■	■



Europe's leading hot melt adhesive specialist. Offering the largest range of performance adhesives and hand-held applicators.



40+ years' experience, offering specialist knowledge on all aspects of commercial gluing operations.



Advanced technology at our UK facility and a continuous programme of research and development ensures that we continue to meet the ever changing needs of industry.



Our adhesives are often formulated using raw materials harvested from sustainable managed forests. Our packaging is recyclable, and where possible, made from recycled materials.



Over 90% of our products are made in Britain, and we offer 12 months' warranty as standard on all equipment.